MBTS threaded holes to be used for HGTD bolting on the Lar EC wall

- 2 double-sided layers of LGADs & ASICs and peripheral electronics
- Front cover with stiffeners
- 30mm Moderator inside the HGTD Vessel
- Back cover
- Outer Drum
- Thermal shield
- Inner Mandrel
- 20mm Moderator outside the HGTD Vessel